MOSFET – Power, N-Channel, SUPERFET III, Easy Drive

650 V, 10 A, 360 mΩ

Description

SUPERFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SUPERFET III MOSFET is very suitable for various power systems for miniaturization and higher efficiency.

Features

- $700 \text{ V} @ \text{T}_{\text{J}} = 150^{\circ}\text{C}$
- Typ. $R_{DS(on)} = 310 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ. $Q_g = 18 \text{ nC}$)
- Low Effective Output Capacitance (Typ. C_{oss(eff.)} = 173 pF)
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

Applications

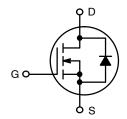
- Computing / Display Power Supplies
- Telecom / Server Power Supplies
- Industrial Power Supplies
- Lighting / Charger / Adapter



ON Semiconductor®

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V _{DSS}	R _{DS(ON)} MAX	I _D MAX	
650 V	360 mΩ @ 10 V	10 A	

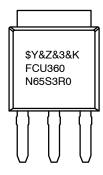


N-Channel MOSFET



I-PAK CASE 369AP

MARKING DIAGRAM



\$Y = ON Semiconductor Logo &Z = Assembly Plant Code &3 = Numeric Date Code &K = Lot Code

FCU360N65S3R0 = Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

ABSOLUTE MAXIMUM RATINGS (T_C = 25°C, Unless otherwise specified)

Symbol	Parameter	Value	Unit	
V _{DSS}	Drain to Source Voltage	650	V	
V_{GSS}	Gate to Source Voltage	DC	±30	V
		AC (f > 1 Hz)	±30	V
I _D	Drain Current	Continuous (T _C = 25°C)	10	Α
		Continuous (T _C = 100°C)	6	1
I _{DM}	Drain Current	Pulsed (Note 1)	25	Α
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		40	mJ
I _{AS}	Avalanche Current (Note 1)	,		Α
E _{AR}	Repetitive Avalanche Energy (Note 1)			mJ
dv/dt	dv/dt MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)	20		
P_{D}	Power Dissipation	(T _C = 25°C)	83	W
		Derate Above 25°C	0.67	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range Maximum Lead Temperature for Soldering, 1/8" from Case for 5 s		-55 to +150	°C
TL			300	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.
1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. $I_{AS} = 2.1 \text{ A}$, $R_G = 25 \Omega$, starting $T_J = 25^{\circ}\text{C}$.
3. $I_{SD} \le 5 \text{ A}$, di/dt $\le 200 \text{ A}/\mu\text{s}$, $V_{DD} \le 400 \text{ V}$, starting $T_J = 25^{\circ}\text{C}$.

THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ hetaJC}$	Thermal Resistance, Junction to Case, Max.	1.5	°C/W
$R_{ hetaJA}$	R _{θJA} Thermal Resistance, Junction to Ambient, Max.		

PACKAGE MARKING AND ORDERING INFORMATION

	Part Number	Top Marking	Package	Packing Method	Reel Size	Tape Width	Quantity
ĺ	FCU360N65S3R0	FCU360N65S3R0	IPAK	Tube	N/A	N/A	75 Units

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS		•	•	•	
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}, T_J = 25^{\circ}\text{C}$	650	_	_	V
		V _{GS} = 0 V, I _D = 1 mA, T _J = 150°C	700	-	_	٧
$\Delta BV_{DSS}/\Delta T_{J}$	Breakdown Voltage Temperature Coefficient	I _D = 1 mA, Referenced to 25°C	-	0.68	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 650 V, V _{GS} = 0 V	-	-	1	μΑ
		V _{DS} = 520 V, T _C = 125°C	-	0.58	-	
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±30 V, V _{DS} = 0 V	_	-	±100	nA
ON CHARACTE	ERISTICS					
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 0.2 \text{ mA}$	2.5	-	4.5	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 5 A	-	310	360	mΩ
9FS	Forward Transconductance	V _{DS} = 20 V, I _D = 5 A	-	6	-	S
YNAMIC CHA	RACTERISTICS		•	•	•	
C _{iss}	Input Capacitance	V _{DS} = 400 V, V _{GS} = 0 V, f = 1 MHz	_	730	_	pF
C _{oss}	Output Capacitance		-	15	-	pF
C _{oss(eff.)}	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	_	173	_	pF
C _{oss(er.)}	Energy Related Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	_	26	_	pF
Q _{g(tot)}	Total Gate Charge at 10 V	V _{DS} = 400 V, I _D = 5 A, V _{GS} = 10 V (Note 4)	_	18	-	nC
Q _{gs}	Gate to Source Gate Charge		_	4.3	_	nC
Q _{gd}	Gate to Drain "Miller" Charge		_	7.6	_	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	1	-	Ω
WITCHING CH	IARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 400 V, I _D = 5 A,	_	12	-	ns
t _r	Turn-On Rise Time	V_{GS} = 10 V, R_g = 4.7 Ω (Note 4)	-	11	-	ns
t _{d(off)}	Turn-Off Delay Time		-	34	-	ns
t _f	Turn-Off Fall Time		_	10	_	ns
OURCE-DRAI	N DIODE CHARACTERISTICS		•	•	•	
I _S	Maximum Continuous Source to Drain Diode Forward Current		-	-	10	Α
I _{SM}	Maximum Pulsed Source to Drain Diode Forward Current		-	-	25	Α
V _{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 5 A	-	-	1.2	٧
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 5 A,	-	241	-	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100 A/μs	_	2.4	-	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS

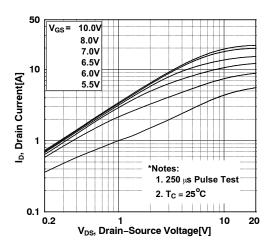


Figure 1. On-Region Characteristics

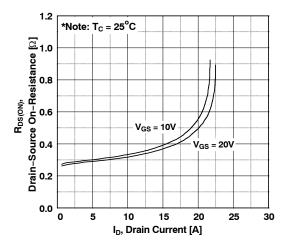


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

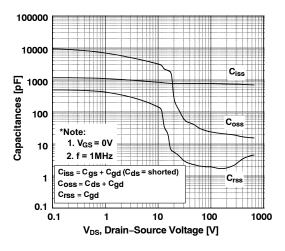


Figure 5. Capacitance Characteristics

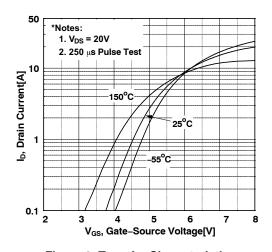


Figure 2. Transfer Characteristics

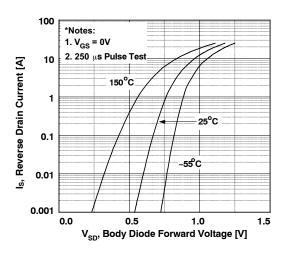


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

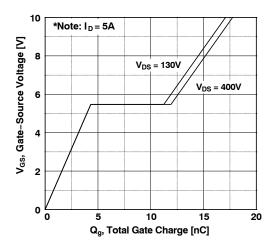


Figure 6. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

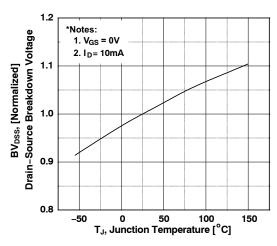


Figure 7. Breakdown Voltage Variation vs. Temperature

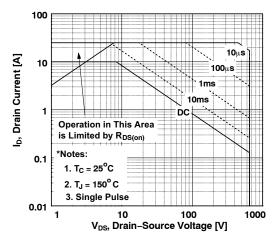


Figure 9. Maximum Safe Operation Area

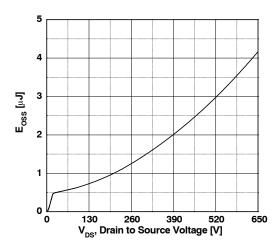


Figure 11. E_{OSS} vs. Drain to Source Voltage

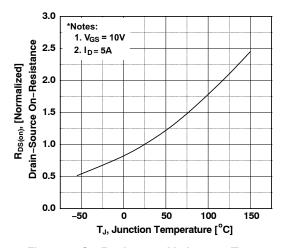


Figure 8. On-Resistance Variant vs. Temperature

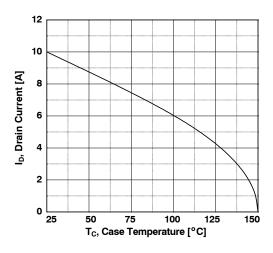


Figure 10. Maximum Drain Current vs. Case Temperature

TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

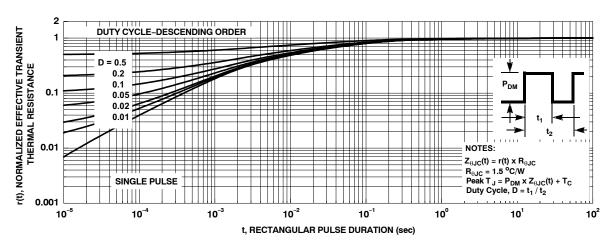


Figure 12. Transient Thermal Response Curve

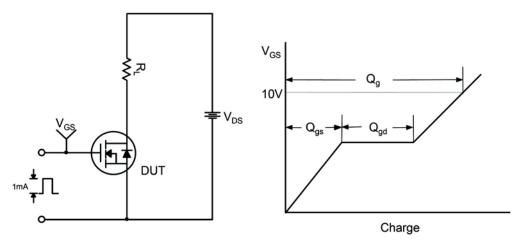


Figure 13. Gate Charge Test Circuit & Waveform

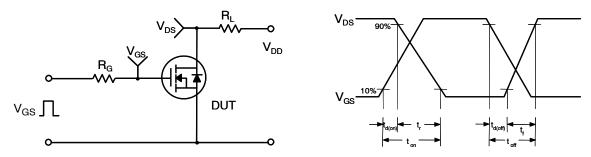


Figure 14. Resistive Switching Test Circuit & Waveforms

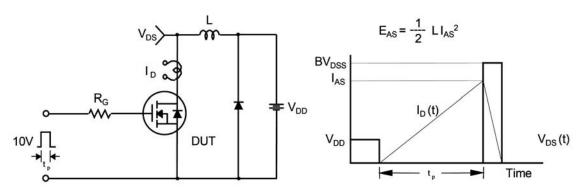
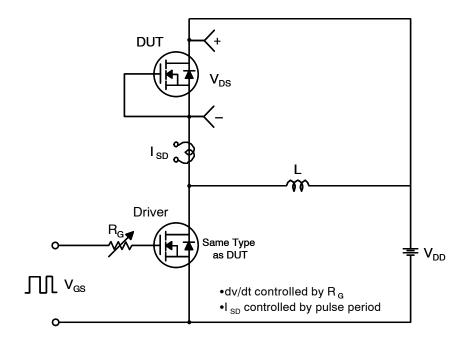


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms



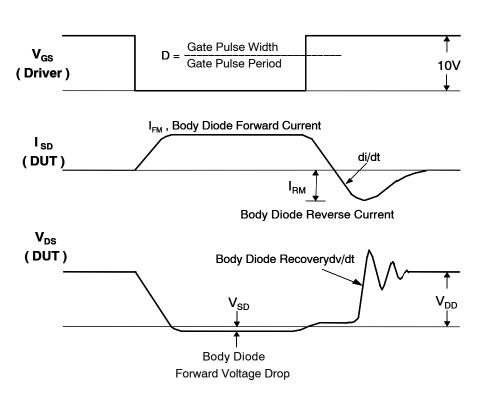
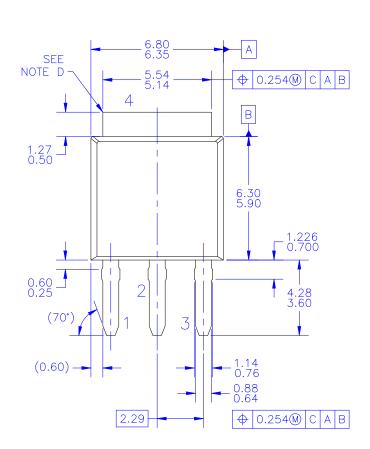


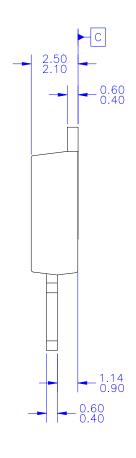
Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms

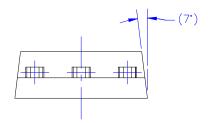
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DPAK3 (STRAIGHT LEADS) CASE 369AP ISSUE O

DATE 30 SEP 2016







NOTES: UNLESS OTHERWISE SPECIFIED

- A) ALL DIMENSIONS ARE IN MILLIMETERS.
- B) PACKAGE BODY REFERENCE: JEDEC, TO-251, ISSUE D, VARIATION AA, DATED JUNE 2002.
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
- D) HEAT SINK TOP EDGE COULD BE IN CHAMFERED CORNERS OR EDGE PROTRUSION.

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